

Title (en)

DEVICE AND METHOD FOR PROCESSING SUBSTRATES

Title (de)

VORRICHTUNG UND VERFAHREN ZUM BEHANDELN VON SUBSTRATEN

Title (fr)

DISPOSITIF ET PROCEDE DE TRAITEMENT DE SUBSTRATS

Publication

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Application

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Priority

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Abstract (en)

[origin: DE19859469A1] A device and method for processing substrates, especially semiconductor wafers, whereby a substrate holder containing a substrate is placed in a processing position above a first processing unit, first processing of the substrate occurs and the substrate holder is raised after said first processing. The invention enables further processing of the substrate to occur in a simple manner requiring little space, whereby the second processing unit moves between the raised substrate holder and the first processing unit and second processing of the substrate is carried out.

IPC 1-7

H01L 21/00

IPC 8 full level

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